Product Change Notice (PCN)

Subject: Add Alternate Assembly Location on DFN-8 Package
Publication Date: 7/22/2021
Effective Date: 10/22/2021

Revision Description:
Initial Release

Description of Change:
Renesas is adding HTC, China as an alternate assembly location for DFN-8 package. Presently, HTC is one of the qualified assembly location for Renesas. The current assembly location for DFN-8 is at CRSS, Malaysia. The material sets of the current and the alternate assembly location are as shown in the below table. There will be changes in the material sets at the alternate location.

No change in moisture sensitive level as a result of this change.

Material Sets	Current Assembly	Alternate Assembly
	CRSS Malaysia	HTC China
Die Attach	HR-5104-25	ATB-120U
Bonding Wire	Copper wire	Copper wire
Mold Compound	G770HCD	CEL-9240

Affected Product List: SPD5108-Y1B000NCG, SPD5108-Y1B000NCG8, SPD5118-Y1B000NCG, SPD5118-Y1B000NCG8.

Reason for Change:
The change is for increased manufacturing capability and business continuity.

Impact on Fit, Form, Function, Quality & Reliability:
The change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the products.

Product Identification:
Assembly lot# with prefix
“MS” denotes CRSS, Malaysia
“HT” denotes HTC, China

Qualification Status: Completed. Refer Appendix A
Sample Availability Date: 6 weeks from sample request date
Device Material Declaration: Available on request

Note:

1. Acknowledgement must be received by Renesas within 30 days or Renesas will consider the change as approved.

2. If timely acknowledgement is provided by Customer, then Customer shall have 90 days from the date of receipt of this PCN to make any objections to this PCN. If Customer fails to make objections to this PCN within 90 days of the receipt of the PCN then Renesas will consider the PCN changes as approved.

3. If customer cannot accept the PCN then customer must provide Renesas with a last time buy demand and purchase order.

For additional information regarding this notice, please contact idt-pcn@lm.renesas.com

Appendix A - Qualification Results

Affected Package: DFN-8
Qual Vehicle: DFN-8
Assembly Material: As shown in page 1
Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Test Descriptions	Test Method	Test Results (Rej/SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - biased (130°C/85% RH, 96 Hrs)	JESD22-A110	0/25	0/25	0/25
* HAST - unbiased (130°C/85% RH, 96 Hrs)	JESD22-A118	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Ball Shear Test	JESD22-B116	0/5	0/5	0/5
Bond Pull Test	MIL-STD-883 (Method 2011)	0/5	0/5	0/5
Physical Dimensions	JESD22-B100	0/30	0/30	0/30
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 1, 260°C	0/25	0/25	-

**Tests were subjected to Preconditioning per JESD22-A113 prior to stress test*